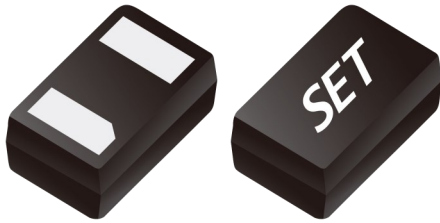


ESD Protection Diodes

Ultra-Low Capacitance ESD and Transient Voltage Protection

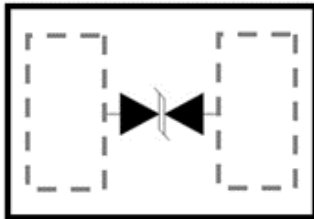
SD0504F10U DFN1006



Description

SD0504F10U is a low-capacitance Transient Voltage Suppressor (TVS) designed to provide electrostatic discharge (ESD) protection for data, control or power lines. With maximum capacitance of 0.4 pF only, SD0504F10U is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4 (± 15 kV air, ± 8 kV contact discharge), very fast charged device model (CDM) ESD and cable discharge event (CDE), etc.

Pinout and Functional Block Diagram



SD0504F10U uses ultra-small DFN1006 package. Each SD0504F10U device can protect one data line. It offers system designers flexibility to protect single data line where space is a premium concern.

Features

- IEC61000-4-2 (ESD) ± 20 kV (Air), ± 20 kV (Contact)
- IEC61000-4-4 (EFT) 40 A (5 / 50 ns)
- IEC61000-4-5 (Lighting) 4 A (8 / 20 μ s)
- 60 Watts Peak Pulse Power Per (tp=8 / 20 μ s)
- Low Capacitance: 0.25 pF (Typical)
- Low Leakage Current
- Low Clamping Voltage
- Flammability Rating: UL 94 V-0
- Halogen Free and RoHS Compliant

Applications

- Serial ATA
- Notebooks, Desktops, Servers
- USB data line protection
- Cellular handsets and accessories
- Display and MDDI ports
- Digital Visual Interfaces (DVI)

Order Information

Type	Package	Marking	Size (mm)	Delivery Form	Delivery Quantity
SD0504F10U	DFN 1006	5B + code (U or L)	1.00 x 0.60 x 0.50	7" T&R	10000 PCS

Limiting Values

(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	20	kV
		IEC 61000-4-2; Air Discharge	-	20	kV
P _{PP}	Peak Pulse Power (8 / 20 μ s)	I _{PP} =4.0 A, t _p =8 / 20 μ s	-	100	W
T _A	Operating Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-55	150	°C

ESD Protection Diodes

Ultra-Low Capacitance ESD and Transient Voltage Protection

SD0504F10U DFN1006

Electrical Characteristics

(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V _{RWM}	Reverse Working Voltage	T _A = 25 °C	-	-	5.0	V
V _{BR}	Breakdown Voltage	I _R = 1 mA; T _A = 25 °C	6.0	-	-	V
I _R	Reverse Leakage Current	V _{RWM} = 5 V; T _A = 25 °C	-	-	0.1	μA
V _C	Clamping Voltage	I _{PP} =1 A, t _p =8 / 20 μs	-	10	13	V
		I _{PP} =2.0 A, t _p =8 / 20 μs	-	-	14	V
		I _{PP} =4.0 A, t _p =8 / 20 μs	-	18	25	V
V _{CTLP}	TLP Clamping Voltage	I _{PP} = 8 A IEC61000-4-2 Level 2 equivalent (± 4 kV Contact, ± 8 kV Air)	-	26	-	V
		I _{PP} = 16 A IEC61000-4-2 Level 4 equivalent (± 8 kV Contact, ± 16 kV Air)	-	38	-	V
C _J	Junction Capacitance	V _R = 0 V, f = 1 MHz	-	0.25	0.4	pF

Performance Curve for Reference

(T_A=25 °C unless otherwise noted)

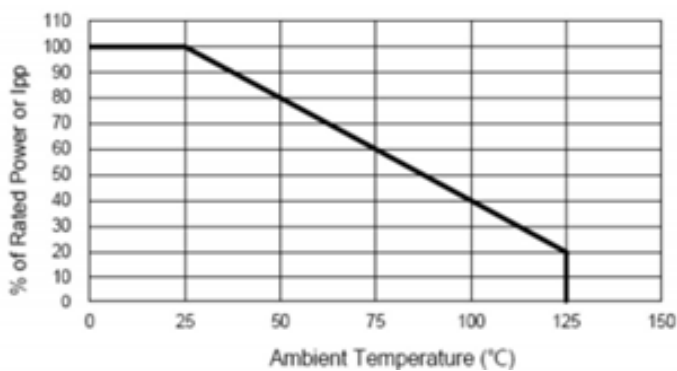


FIGURE 1
Power Derating Curve

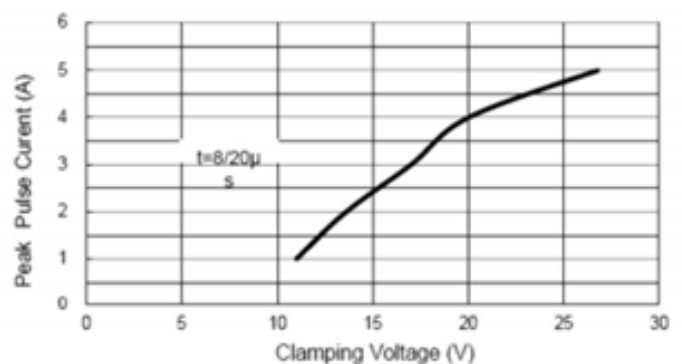


FIGURE 2
Clamping Voltage VS. Peak Pluse Current

ESD Protection Diodes

Ultra-Low Capacitance ESD and Transient Voltage Protection

SD0504F10U DFN1006

Performance Curve for Reference

($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

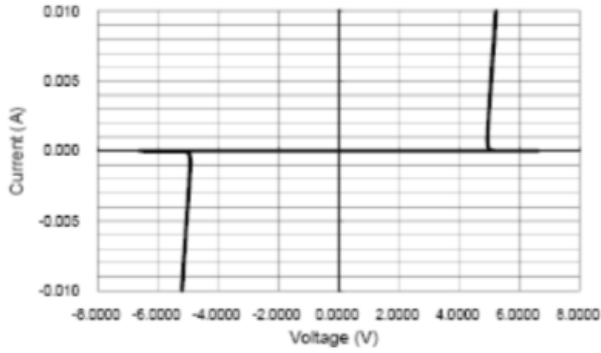


FIGURE 3
Voltage Sweeping

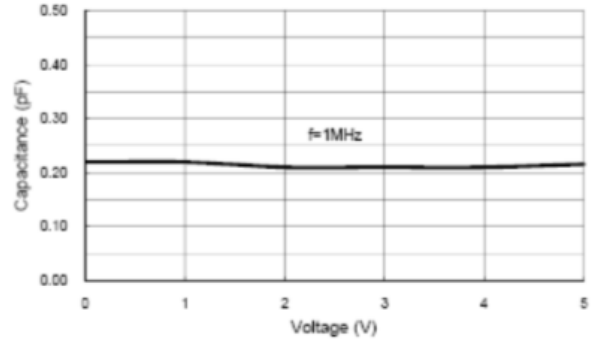


FIGURE 4
Voltage VS. Capacitance

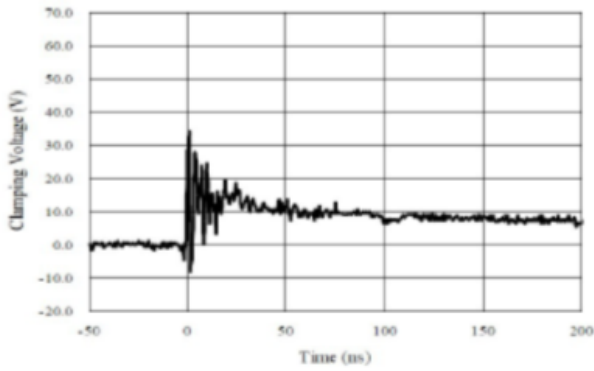


FIGURE 5
ESD Clamping

(+8 kV Contact Per IEC 61000-4-2)

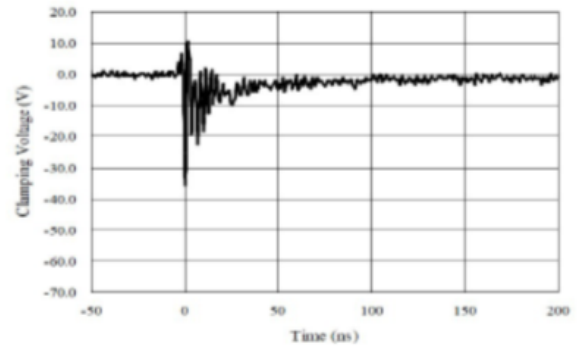


FIGURE 6
ESD Clamping

(-8 kV Contact Per IEC 61000-4-2)

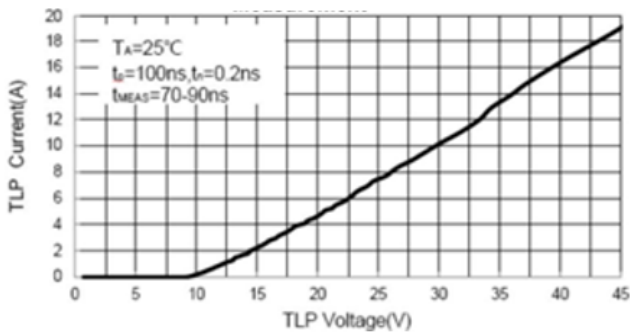


FIGURE 7

Transmission Line Pulsing (TLP) Measurement

ESD TVS

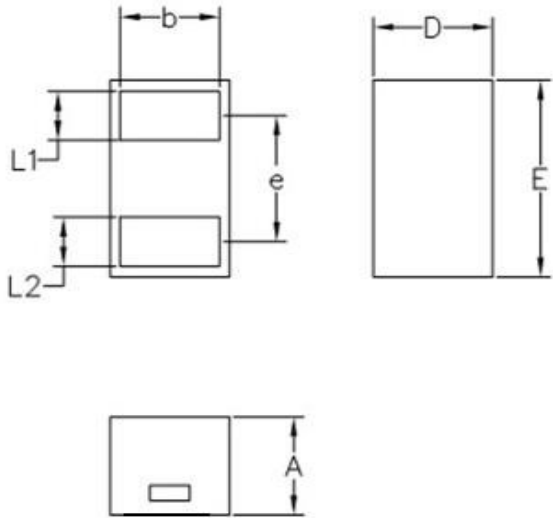
ESD TVS

ESD Protection Diodes

Ultra-Low Capacitance ESD and Transient Voltage Protection

SD0504F10U DFN1006

Package Dimensions - DFN1006



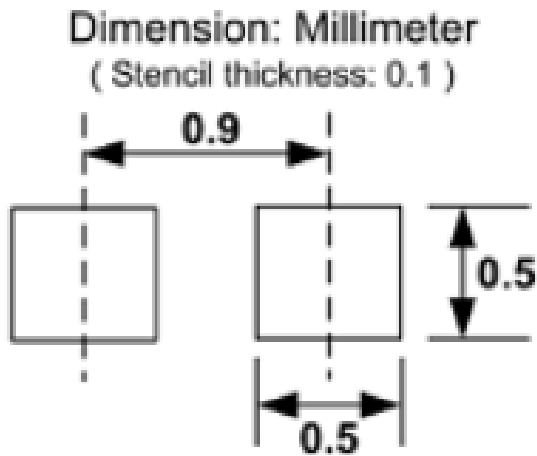
Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
D	0.55	0.65	0.022	0.026
E	0.95	1.05	0.037	0.041
L1	0.20	0.30	0.008	0.012
L2	0.20	0.30	0.008	0.012
A	0.45	0.55	0.018	0.022
b	0.45	0.55	0.018	0.022
e	0.64 BSC		0.025 BSC	

ESD TVS

ESD TVS

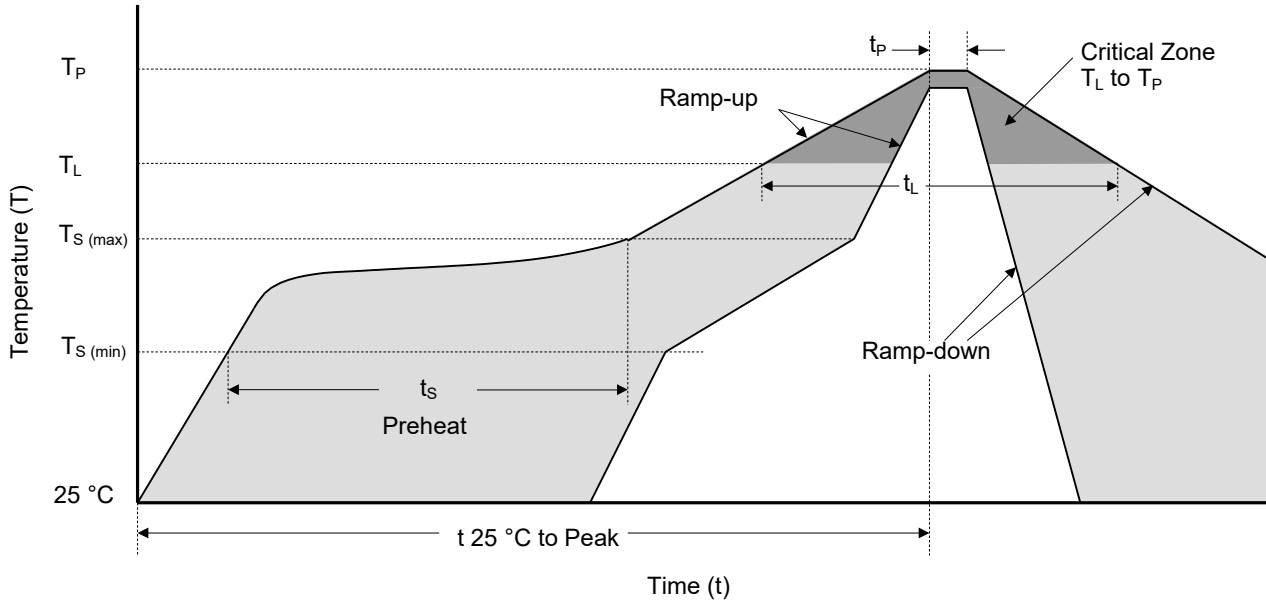
Recommended Solder Pad Footprint

(Ratings at 25 °C ambient temperature unless otherwise specified.)



Soldering Footprint

Soldering Parameters



Reflowing Condition

Reflow Soldering Parameters		Lead-Free Assembly
Pre-heat	Temperature Min ($T_{S (min)}$)	150 °C
	Temperature Max ($T_{S (max)}$)	200 °C
	Time (min to max) (t_s)	60 ~ 120 seconds
Average Ramp Up Rate (Liquidus Temp (T_L) to Peak)		3 °C / second max.
$T_{S (max)}$ to T_L Ramp-up Rate		3 °C / second max.
Reflow	Temperature (T_L) (Liquidus)	217 °C
	Time (min to max) (t_L)	60 ~ 150 seconds
Peak Temperature (T_P)		260 ^{+0/-5} °C
Time of within 5 °C of Actual Peak Temperature (t_p)		20 ~ 40 seconds
Ramp-down Rate		6 °C / second max.
Time from 25 °C to Peak Temperature		8 Minutes max.
Do Not Exceed		260 °C

ESD TVS

ESD TVS



ATTENTION

Usage

1. TVS must be operated in the specified ambient temp.
2. Do not clean the TVS with strong polar solvent such as ketone, esters, benzene and halogenated hydrocarbon, to avoid damaging the encapsulating layer.
3. Please do not apply severe vibration, shock or pressure to TVS, to avoid element cracking.

Replacement

1. If TVS is visually damaged, please replace it.
2. TVS is a non-repairable product. For safety sake, please use equivalent TVS for replacement.

Storage

1. Storage Temp. Range: (-55 to 150) °C.
2. Do not store the TVS at the high temp., high humidity or corrosive gas environment, to avoid influencing the solder-ability of the lead wires. The product shall be used up within 1 year after receiving the goods.

Environmental Conditions

1. TVS should not be exposed to the open air, nor direct sunshine.
2. TVS should avoid rain, water vapor or other condition of high temp. and high humidity.
3. TVS should avoid sand dust, salt mist, or other harmful gases.

Max. Typical Capacitance of TVS

1. The typical capacitance of TVS is listed in the specifications. Designers may refer to it when designing TVS in High frequency circuit.

Installation Mechanical Stress

1. Do not knock TVS when installing, to avoid mechanical damage.
2. Please do not apply severe vibration, shock or pressure to TVS, to avoid surface resin or element cracking.